

LINEAR TECHNOLOGY MATERIALS DECLARATION

ltc1390cn#pbf

(Engineering Calculation)

PDIP

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TOTAL MASS (g) : 1.01859

| COMPONENT MATERIAL | VENDOR/ INDUSTRY NAMES | CONSTITUENT NAME | CAS NUMBER | CONSTITUENT MASS (g) | CONSTITUENT (PPM) OF MATERIAL | CONSTITUENT (PPM) OF TOTAL PKG. | | |
|--------------------------------|----------------------------------|--------------------------------|------------|----------------------|-------------------------------|---------------------------------|----------------|---------------------|
| Active Device | Linear Technology | Silicon (Si) | 7440-21-3 | 0.001460 | 1000000 | 1433.35400391 | | |
| Die Coat | Dow Corning | Silicone | 69430-27-9 | 0.000000 | 0 | 0 | | |
| Lead Frame | Cu | Copper (Cu) | 7440-50-8 | 0.313072 | 975000 | 307358.21875 | | |
| | | Iron (Fe) | 7439-89-6 | 0.007706 | 24000 | 7565.35986328 | | |
| | | Phosphorus (P) | 7723-14-0 | 0.000096 | 300 | 94.2479400635 | | |
| | | Zinc (Zn) | 7440-66-6 | 0.000225 | 700 | 220.893585205 | | |
| | | Nickel (Ni) | 7440-02-0 | 0.000000 | 0 | 0 | | |
| | | Silicon (Si) | 7440-21-3 | 0.000000 | 0 | 0 | | |
| | | Magnesium (Mg) | 7439-95-4 | 0.000000 | 0 | 0 | | |
| | | Tin (Sn) | 7440-31-5 | 0.000000 | 0 | 0 | | |
| Lead Frame Total: | | | | 0.321099 | 1000000 | 315238.75 | | |
| Plating | PMI | Exter. Plating Pb | 7439-92-1 | 0.000000 | 0 | 0 | | |
| | | Exter. Plating Sn | 7440-31-5 | 0.024547 | 1000000 | 24098.984375 | | |
| | | External Plating Total: | | | | 0.024547 | 1000000 | 24098.984375 |
| | | Inter. Plating Ni | 7440-02-0 | 0.000000 | 0 | 0 | | |
| | | Inter. Plating Ag | 7440-22-4 | 0.002569 | 1000000 | 2522.11401367 | | |
| Internal Plating Total: | | | | 0.002569 | 1000000 | 2522.11401367 | | |
| Die Attach | ELECTRICALLY CONDUCTIVE ADHESIVE | Silver (Ag) | 7440-22-4 | 0.000558 | 750000 | 547.816101074 | | |
| | | Tin (Sn) | 7440-31-5 | 0.000000 | 0 | 0 | | |
| | | Lead (Pb) | 7439-92-1 | 0.000000 | 0 | 0 | | |
| | | Silica (SiO2) | 60676-86-0 | 0.000000 | 0 | 0 | | |
| | | Indium (In) | 7440-74-6 | 0.000000 | 0 | 0 | | |
| | | Metal Oxide | | 0.000000 | 0 | 0 | | |
| | | Antimony (Sb) | 7440-36-0 | 0.000000 | 0 | 0 | | |
| | | Resin (EP) | | 0.000186 | 250000 | 182.605377197 | | |
| Die Attach Total: | | | | 0.000744 | 1000000 | 730.421508789 | | |
| Encapsulation | FILLED EPOXY RESIN | Resin (EP) | | 0.160224 | 240000 | 157299.796875 | | |
| | | Bromine (Br) | 40039-93-8 | 0.006676 | 10000 | 6554.15820312 | | |
| | | Silica (SiO2) | 60676-86-0 | 0.480672 | 720000 | 471899.375 | | |
| | | Antimony Trioxide (Sb2O3) | 1309-64-4 | 0.020028 | 30000 | 19662.4746094 | | |
| | | Metal Hydroxide | | 0.000000 | 0 | 0 | | |
| | | Carbon Black (C) | 1333-86-4 | 0.000000 | 0 | 0 | | |
| | | Encapsulation Total: | | | | 0.667600 | 1000000 | 655415.8125 |
| Bond Wire Estimated | AFW/TANAKA/ Kn | Gold (Au) | 7440-57-5 | 0.000571 | 1000000 | 560.578857422 | | |
| | | | | | TOTAL MASS (g) : | 1.01859 | | |